UL 60950 (File No.E108430)

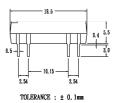
#### **Features**

- 1. Molded epoxy body.
- 2. Dip type construction with the same terminal pitch as ICs or TTLs simplifies PC board designing. In addition, the high sensitivity allows direct driving by TTL, etc.
- 3. Automatic insertion compatible.
- 4. Sealed construction permits automatic flow soldering and cleaning.
- 5. Diode & Magnetic shield are available.

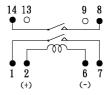
## Outside Dimension:Unit (mm)







# **Schematic:Top View**



# **Coil Ratings**

(AT 20°C)

<del>-</del>		(Al 20 0)
Parameter	Rating	Unit
Coil Resistance	500	Ω( ±10%)
Nominal Coil Voltage	12	VDC
Maximun Continuous Voltage	20	VDC
Must Operate	9	VDC
Must Release	1.2	VDC
Rated Current	24	mA

## **Electrical Characteristics**

Parameter	Rating	Unit
Contact Resistance	100	mΩ (max)
Operate Time	0.5	ms(max)
Bounce Time	0.5	ms(max)
Release Time	0.2	ms(max)
Insulation Resistance (100VDC)	10 <sup>11</sup>	Ω (min)
Power	10	VA(max)
Switching Voltage	200	VDC(max)
Switching Current	0.5	A(max)
Carry Current	1.0	A(max)
Breakdown Voltage ( Across Open Contact )	250	VDC(min)
( Between Coil & Contact )	500	VDC(min)
Life Expectancy (Signal Level)	10 <sup>8</sup>	
Operating Temp	-40 to 85	°C
Storage Temp	-50 to125	°C
Resonant Frequency	3.5	KHZ
Vibration ( 10-2000HZ )	20	9(max)
Minimum Permissible Load	100	mVDC 10μA